# LNJ115W8ARA

## Surface Mounting Chip LED

TSS Bi-Color Type

### ■ Absolute Maximum Ratings $T_a = 25$ °C

#### • Green

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_F$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	$V_R$	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### Orange

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	$V_R$	3	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

## ■ Electro-Optical Characteristics $T_a = 25$ °C

#### • Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	$I_{O}$		1.8	5.0		mcd
Forward current	$I_{\mathrm{F}}$			10		mA
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm
Reverse current	$I_R$	$V_R = 4 V$			10	μΑ

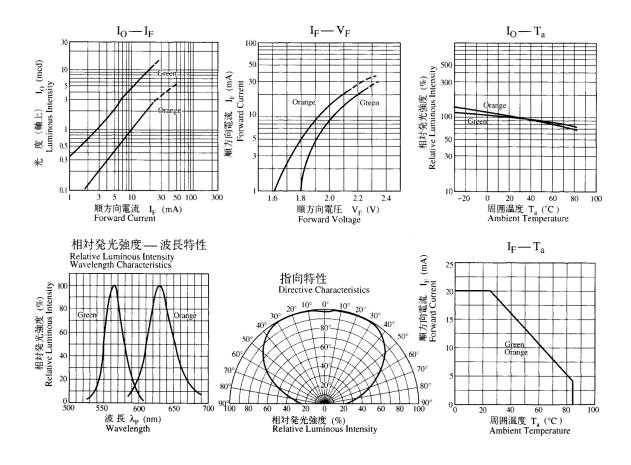
## ■ Lighting Color / Lens Color

- Green / White Diffused
- Orange / White Diffused

### ■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

### • Orange

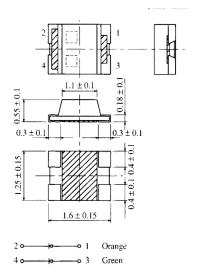
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	$I_{O}$		0.4	1.0		mcd
Forward current	$I_{\mathrm{F}}$			10		mA
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		1.93	2.6	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		40		nm
Reverse current	$I_R$	$V_R = 3 V$			10	μΑ



2 SHD00585AEK

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## ■ Package (Unit: mm)



- Pin name
  - 1: Anode
- 2: Cathode
- 3: Anode
- 4: Cathode

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